

## AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method comprising:  
contiguously applying a thermoplastic bonder to perimeters of a ball grid array (BGA) package, wherein contiguously applying includes applying an application of the thermoplastic bonder at an equal distance from applications next to the application, wherein the thermoplastic bonder is applied to the BGA package directly between a first surface and a second surface of the BGA package such that the thermoplastic bonder remains at the perimeters of the BGA package between the first surface and the second surface;  
applying the thermoplastic bonder to solder balls of the BGA package, wherein the thermoplastic bonder is applied to the solder balls between the first surface of the BGA package and the solder balls, and between the second surface of the BGA package and the solder balls; and  
attaching a printable circuit board (PCB) to the BGA package.
2. (Previously Presented) The method of claim 1, wherein the BGA package comprises an integrated circuit (IC) device.
3. (Previously Presented) The method of claim 1, wherein the first surface comprise a top surface, and the second surface comprises a bottom surface.
4. (Previously Presented) The method of claim 1, further comprising preventing warpage of the BGA package by applying the thermoplastic bonder in a weakest area of the BGA package, the weakest area including the perimeters of the BGA package; wherein the BGA package includes one or more of an opening of the

BGA package, a cracking of the BGA package, a curving of the BGA package, bending, and a breaking of the BGA package.

5. (Previously Presented) The method of claim 1, wherein the applying of the thermoplastic bonder to the perimeters of the BGA package further comprises applying the thermoplastic bonder between the first surface and the second surface of the BGA package such that the thermoplastic bonder is applied exclusively to the perimeters of the BGA package, wherein the perimeters include one or more of edges and corners of the BGA package.
6. (Previously Presented) The method of claim 4, further comprising determining the weakest area of the BGA package to prevent the warpage.
7. (Cancelled)
8. (Previously Presented) The method of claim 1, wherein the thermoplastic bonder is applied via one or more of a hot melting jig and a dispenser.
9. (Cancelled)
10. (Currently Amended) The method of claim 8, wherein the thermoplastic bonder is further applied via software to control placement distance of the thermoplastic bonder to the perimeters of the BGA package with respect to the solder balls of the BGA package.
- 11-31 (Cancelled)